

XP BOND™

Universal Total-Etch Adhesive

CAUTION: For dental use only. Rx only.

XP BOND™ Universal Total-Etch Adhesive is a universal self-priming dental adhesive system designed to bond resin based materials to enamel and dentin as well as to metals and ceramic.

XP BOND™ Universal Total-Etch Adhesive stands for *eXtra Performance* due to high bond strength to enamel and dentin, easy and comfortable application and a high degree of technique robustness.

XP BOND™ Universal Total-Etch Adhesive is designed to be used with resin based restorative materials and cements. When mixed with Self Cure Activator, XP BOND™ Universal Total-Etch Adhesive is designed to be used with DENTSPLY manufactured dual cure/self-cure resin cement such as Calibra® Esthetic Resin Cement to bond all indirect restorations including metal, ceramic and composite crowns, inlays, onlays, veneers and bridge retainers. Bonding of endodontic posts when used with Calibra® Esthetic Resin Cement, and bonding of DENTSPLY manufactured dual cured composite restoratives such as FluoroCore®2 Fluoride Releasing Core Build-up Material to enamel and dentin also occurs with this system. When used with the Amalgam Bonding Accessory Kit, available separately, the XP BOND™ Universal Total-Etch Adhesive also adhesively bonds fresh amalgam to enamel and dentin.

XP BOND™ Universal Total-Etch Adhesive is designed to be used following phosphoric acid conditioning. Caulk® 34% Tooth Conditioner Gel is included in the XP BOND™ Universal Total-Etch Adhesive Introductory Kits (*see complete Directions for Use prior to use*). Use of other dentin/enamel conditioners, resin cements, dual/self-cured composites or adhesives with XP BOND™ Universal Total-Etch Adhesive is at the discretion and sole responsibility of the dental practitioner.

COMPOSITION

XP BOND™ Universal Total-Etch Adhesive:

Carboxylic acid modified dimethacrylate (TCB resin); Phosphoric acid modified acrylate resin (PENTA); Urethane Dimethacrylate (UDMA); Triethyleneglycol dimethacrylate (TEGDMA); 2-hydroxyethylmethacrylate (HEMA); Butylated benzenediol (stabilizer); Ethyl-4-dimethylaminobenzoate; Camphorquinone; Functionalized amorphous silica; t-butanol

Self Cure Activator:

Urethane Dimethacrylate (UDMA); 2-hydroxyethylmethacrylate (HEMA); Catalyst; Photoinitiators; Stabilizers; Acetone; Water

INDICATIONS

1. Direct, light-cured composite and compomer restorative.
2. Indirect Restorations; light-cured, resin cemented veneers.
3. Composite, ceramic and amalgam repairs.
4. Cavity varnish for use with fresh amalgam.
5. Direct, dual cure or self-cure composite restorations and core build-ups.
6. Indirect restorations; dual cured and self-cured resin cemented inlays, onlays, crown and bridge retainers.
7. Dual cured and self cured resin cemented endodontic post cementation.
8. Adhesive bonding of direct amalgam restoration.

CONTRAINDICATIONS

1. XP BOND™ Universal Total-Etch Adhesive is contraindicated for use with patients who have a history of allergic reaction to methacrylate resins or any of the components.

2. **XP BOND™ Universal Total-Etch Adhesive** is contraindicated for direct application to dental pulp tissue (direct pulp capping).

WARNINGS

1. **XP BOND™ Universal Total-Etch Adhesive** contains polymerizable methacrylate monomers. Avoid prolonged or repeated contact with skin (allergic contact dermatitis), oral soft tissues, and eyes. Avoid prolonged inhalation. Do not take internally.
Eye contact: **XP BOND™ Universal Total-Etch Adhesive** contains methacrylates which may be irritating to eyes. Before using this product wear protective glasses as well as covering the patient's eyes to protect from splashing material. In case of contact with eyes, rinse immediately with plenty of water and seek medical attention.
Skin contact: **XP BOND™ Universal Total-Etch Adhesive** contains polymerizable monomers which can cause skin sensitization (allergic contact dermatitis) in susceptible individuals. If contact with skin occurs immediately wipe off thoroughly with cotton and alcohol and then wash well with soap and water after contact. If skin rash and sensitization or other allergic reaction occurs discontinue use and seek medical attention.
Oral mucosa contact: Avoid contact with oral soft tissues. If accidental contact occurs, flush mucosa with plenty of water and expectorate water. If sensitization of mucosa persists, seek medical attention immediately.
2. **XP BOND™ Universal Total-Etch Adhesive** contains t-butanol. **Self Cure Activator** contains acetone. Do not breathe vapor.

PRECAUTIONS

1. This product is intended to be used only as specifically outlined in the *Directions for Use*. Any use of this product inconsistent with the *Directions for Use* is at the discretion and sole responsibility of the practitioner.
2. Wear suitable protective eyewear, clothing and gloves. Protective eyewear is recommended for patients.
3. Contact with saliva, blood and/or some astringent solutions during adhesive procedures may cause failure of the restoration. Use of rubber dam or adequate isolation is recommended.
4. The **XP BOND™ Universal Total-Etch Adhesive** bottles should be tightly closed immediately after use.
5. **XP BOND™ Universal Total-Etch Adhesive** is light-cured material. Proceed immediately once materials have been placed in mixing well or close the **CliXdish™** Mixing Well lid to protect material from ambient light. The components are cured by visible light.
6. Once **XP BOND™ Universal Total-Etch Adhesive** is mixed with **Self Cure Activator**, apply immediately onto prepared tooth surfaces.
7. Use only in well ventilated areas.
8. **Flammable:** **XP BOND™ Universal Total-Etch Adhesive** contains t-butanol. **Self Cure Activator** contains acetone. Keep away from sources of ignition.
9. Avoid **XP BOND™ Universal Total-Etch Adhesive** components saturating the gingival retraction cord. If **XP BOND™ Universal Total-Etch Adhesive** components soak into cord, they may set hard and bond the cord to the underlying tooth surface making cord removal difficult.
10. Single dose containers are intended for single use only, and should be discarded after use. Do not re-seal or re-use.

STORAGE

XP BOND™ Universal Total-Etch Adhesive should be kept out of direct sunlight and stored in a well ventilated place. Store **XP BOND™ Universal Total-Etch Adhesive** at temperatures between 10°C/50°F – 28°C/82°F. Store **Self Cure Activator** at room temperature not exceeding 24°C/75°F. Refrigerated storage of **Self Cure Activator** is not required, but is acceptable when not in use. Allow materials to reach room temperature prior to use. Protect from moisture. Do not freeze. Do not use after expiration date.

ADVERSE REACTIONS

Product may irritate the eyes and skin. **Eye contact:** irritation and possible corneal damage. **Skin contact:** irritation or possible allergic response. Reddish rashes may be seen on the skin. **Mucous membranes:** inflammation, edema, sloughing. (See *Warnings*)

INTERACTIONS

1. Eugenol-containing dental materials should not be used in conjunction with this product because they may interfere with hardening and cause softening of the polymeric components of the material.
2. Insufficient data exist to support the use of desensitizing agents and/or cavity cleansing agents with XP BOND™ Universal Total-Etch Adhesive. Recommended pre-treatment is pumice or prophylaxis paste with a rubber cup. (See *Step-by-Step Instructions*)
3. Exercise caution if mineral-impregnated (e.g., ferric compounds) retraction cords and/or hemostatic solutions are used in conjunction with adhesive procedures. In vitro studies have suggested compromised adhesive bond strength to enamel and dentin contaminated with hemostatic agents. Marginal seal may be adversely affected, allowing microleakage, subsurface staining and/or restoration failure. If gingival retraction is necessary, use of plain, non-impregnated cord is recommended.
4. If H₂O₂ has been used to clean the cavity, proper rinsing is essential. Higher concentration H₂O₂ may interfere with the setting of polymerizable material and should not be used prior to the application of XP BOND™ Universal Total-Etch Adhesive.
5. The use of a dual cure adhesive such as XP BOND™ Universal Total-Etch Adhesive with Self Cure Activator can shorten working time of a dual cure resin cement system. This effect should be investigated in the laboratory prior to clinical use.
6. Variable in-vitro data exist regarding use of light-cured-only adhesives such as XP BOND™ Universal Total-Etch Adhesive without Self Cure Activator in conjunction with dual-cured or self-cured resin restorative or cement materials in limited or no light curing applications. Chemical/Product incompatibility may adversely affect product efficacy, leading to premature restoration failure.

STEP-BY-STEP INSTRUCTIONS FOR USE

Light Cured

1. **Direct restoration** (light cured composite resin and compomers)
 - 1.1 **Cleaning:** Clean uninstrumented enamel and dentin with a rubber cup and pumice or a cleaning paste such as Nupro® Prophylaxis Paste. Wash thoroughly with water spray and air dry. Clean freshly instrumented enamel and dentin with water spray and then air dry.
 - 1.2 **Pulp Protection:** In deep cavities/preparations, cover the dentin close to the pulp (less than 1mm) with a hard setting calcium hydroxide liner (Dycal® Liner) leaving the rest of the cavity surface free for bonding with XP BOND™ Universal Total-Etch Adhesive.
 - 1.3 **Tooth Conditioning/Dentin Pretreatment:** When used as a bonding agent for direct, restorative materials, it is recommended to follow the total etch technique described in 1.3.1. Prior to use, please see complete *Directions for Use* for Caulk® 34% Tooth Conditioner Gel.
 - 1.3.1 Application of Caulk® 34% Tooth Conditioner Gel (34% phosphoric acid)
After application of rubber dam or other suitable isolation technique, apply Caulk® 34% Tooth Conditioner Gel. Attach disposable needle to end of syringe. Needle tip may be bent for easy access. Gently extrude Caulk® 34% Tooth Conditioner Gel to the cavity surfaces starting at the enamel margins. For best results, condition enamel for at least 15 seconds and dentin for 15 seconds or less.
 - 1.3.2 Rinsing and Blot Drying: Remove gel with aspirator tube and/or vigorous water spray and rinse conditioned areas thoroughly for at least 15 seconds. Remove rinsing water completely by blowing gently with an air syringe or by blot drying with a cotton pellet. Do not desiccate dentin. Proceed immediately to application of XP BOND™ Universal Total-Etch Adhesive.
 - Once the surfaces have been properly treated, **they must be kept uncontaminated.** If salivary contamination occurs, thoroughly clean with vigorous water spray, dry, and repeat conditioning procedure of enamel for 5 seconds only. Rinse and dry as described above.
 - 1.4 **Application of XP BOND™ Universal Total-Etch Adhesive**
 - 1.4.1 **Conventional Bottle:** Dispense XP BOND™ Universal Total-Etch Adhesive directly onto a clean disposable brush provided, making sure that the bottle does not come in direct contact with the brush, or place 2-3 drops of XP BOND™ Universal Total-Etch Adhesive into a clean CiiXdish™ Mixing Well or standard dappen dish or mixing well. Replace cap promptly. **Technique Tip:** Material in a closed CiiXdish™ Mixing Well will remain usable for up to 15 minutes. Material dispensed to a standard mixing well must be used immediately.

Unit Dose Container: Grasp container at each end, or insert into holder, placing thumb along center score. Firmly apply pressure until container separates. Holder may be placed on the tabletop or held between fingers for convenience. Insert disposable applicator into opening to saturate applicator tip.

- 1.4.2 Using the disposable brush supplied, apply XP BOND™ Universal Total-Etch Adhesive to wet all the tooth surfaces uniformly. Avoid pooling. This surface should remain undisturbed for 20 seconds.
- 1.4.3 Evaporate solvent by thoroughly drying with clean, dry air from a dental syringe for at least 5 seconds. Surface should have a uniform glossy appearance. If not, repeat application and air dry.
- 1.4.4 Cure XP BOND™ Universal Total-Etch Adhesive for 10 seconds¹ using a curing light.
- 1.5 **Completion:** Place light-cured restorative material over the cured XP BOND™ Universal Total-Etch Adhesive as per restorative material manufacturer's directions.
2. **Veneer cementation** (light cured resin cement)
 - 2.1 **Cleaning:** See Section 1.1
 - 2.2 **Tooth Conditioning/ Dentin pretreatment:** See Section 1.3
 - 2.3 **Application of XP BOND™ Universal Total-Etch Adhesive:** Apply and light cure XP BOND™ Universal Total-Etch Adhesive as described for direct restorations, see Section 1.4.
 - 2.4 **Preparation of restoration**
 - 2.4.1. Treat surface of restoration according to manufacturers or dental laboratory's instructions, i.e., etching, mechanical roughening and/or Calibra® Silane Coupling Agent (available separately, see complete *Directions for Use*) application.
 - 2.4.2 Apply a single coat of XP BOND™ Universal Total-Etch Adhesive to the internal bonding surface of the restoration. Immediately air dry for 5 seconds.
 - 2.4.3 Light curing of applied XP BOND™ Universal Total-Etch Adhesive is not necessary.
 - 2.5 **Cementation:** Prepare and apply light-cured resin cement according to manufacturer's instructions.
3. **Composite, ceramic and amalgam repairs** (light cured composite resin and compomers)
 - 3.1 **Preparation, Cleaning:** Roughen the fractured restoration surface with a fine diamond bur. Create mechanical retention where possible.
 - 3.2 **Tooth Conditioning/Dentin Pretreatment:** Etch tooth with Caulk® 34% Tooth Conditioner Gel as outlined in Section 1.3. Etch ceramic restoration repair area with hydrofluoric acid according to manufacturer's instructions.
 - 3.3 **Treatment of the Restoration:** Rinse with water for 10 seconds. Air dry. **NOTE:** Apply Calibra® Silane Coupling Agent to porcelain surfaces to be repaired following manufacturer's instructions.
 - 3.4 **Application of XP BOND™ Universal Total-Etch Adhesive:** Apply and light cure¹ XP BOND™ Universal Total-Etch Adhesive as described for direct restorations, see Section 1.4.
 - 3.5 **Completion:** Complete repair with placement and curing of desired shade(s) of light cured composite restorative following manufacturer's directions.
4. **Cavity varnish for use with fresh amalgam**

When used as a cavity varnish, XP BOND™ Universal Total-Etch Adhesive is not an amalgam adhesive.

 - 4.1 **Preparation:** Finish preparation by removing existing restorations and/or caries.
 - 4.2 **Cleaning:** Clean preparation and place Dycal® Liner if needed, following Section 1.1 and 1.2.
 - 4.3 **Tooth Conditioning/Dentin Pretreatment:** Rinse and carefully air-dry cavity preparation, but do not desiccate exposed dentin. Condition enamel and dentin following Section 1.3.
 - 4.4 **Application of XP BOND™ Universal Total-Etch Adhesive:** Apply and light cure XP BOND™ Universal Total-Etch Adhesive as described for direct restorations, see section 1.4.
 - 4.5 **Completion:** Place and condense amalgam (e.g. Dispersalloy® Dispersed Phase Alloy) as per manufacturer's directions.

STEP-BY-STEP INSTRUCTIONS

Dual Cured

5. **Direct restorations** (Dual Cure or Self-Cure composite/core build-up)
 - 5.1 **Preparation:** Finish preparation by removing existing restorations and/or caries.

- 5.2 **Cleaning:** Clean preparation and place Dycal® Liner if needed, following Section 1.1 and 1.2.
- 5.3 Place pin, post or matrix as needed.
- 5.4 **Tooth Conditioning/Dentin Pretreatment:** When used as a bonding agent for composite materials, it is recommended to follow the total etch technique described in Section 1.3.
- 5.5 **Application of XP BOND™ Universal Total-Etch Adhesive**
 - 5.5.1 Place 1-2 drops of XP BOND™ Universal Total-Etch Adhesive into a clean Clixdish™ Mixing Well or standard plastic mixing well. Replace cap promptly.
 - 5.5.2 Place an equal number of drops of Self Cure Activator into the same mixing well. Replace cap promptly. Mix contents for 1-2 seconds with a clean, unused brush tip.
 - 5.5.3 Using the disposable brush supplied, apply mixed adhesive/activator to wet all the tooth surfaces uniformly. Avoid pooling. These surfaces should remain undisturbed for 20 seconds.
 - 5.5.4 Remove solvent by gently drying with clean, dry air from a dental syringe for at least 5 seconds. Surface should have a uniform glossy appearance. If not, repeat application and air dry. Surface should not show areas of excessive adhesive thickness or pooling. Repeat air drying/evaporation outlined above if necessary. **LIGHT CURING NOTE:** Light curing of applied XP BOND™ Universal Total-Etch Adhesive and activator mixture is not necessary when used in conjunction with DENTSPLY manufactured dual or self cure resin restoratives. If curing is desired, cure mixed adhesive/activator for 10 seconds' using a curing light.
- 5.6 Dispense and mix dual cure or self cure composite per manufacturer's directions.
- 5.7 **Placement of self cure composite material:** Follow Section 5.7.2, Chemical Self Cure, below.
Placement of dual cure composite material: Any of the following placement techniques are acceptable. The preferred method is to use both visible light and chemical self cure. (See Step 5.7.3 Dual Cure)
 - 5.7.1 Visible Light Cure: Place mixed material directly in increments and light cure each increment per manufacturer's instructions.
 - 5.7.2 Chemical Self Cure: Place large increment(s) or load mixed material into a clear crown form and seat onto the preparation. Allow to self cure per manufacturer's instructions. Visible Light Curing of external surface is optional, but advisable.
 - 5.7.3 Dual Cure: After placing the first increment, and light-curing, large increments may then be placed or material loaded into a clear crown form and seated onto the preparation. Allow to self cure per manufacturer's instructions. Visible Light Curing of external surface is optional, but advisable.
- 5.8 **Finishing:** After allowing manufacturer's recommended set time, remove matrix, and apply an optional but advisable surface light curing. Gross reduction may begin immediately.
6. **Indirect restorations** (Dual Cure inlays, onlays, crowns and bridge retainers)
 - 6.1 **Cleaning:** See section 1.1
 - 6.2 **Tooth Conditioning/Dentin Pretreatment:** When used as a bonding agent for inlays or onlays, crowns and bridge retainers, it is recommended to follow the total etch technique described in Section 1.3. Once the surfaces have been properly treated, they must be kept uncontaminated. If salivary contamination occurs, repeat procedure beginning at Step 6.1.
 - 6.3 **Application of XP BOND™ Universal Total-Etch Adhesive:** When used as a bonding agent for inlays, onlays, crowns or bridge retainers, it is recommended to follow the dual cure mixed adhesive/activator application technique described in Section 5.5. **LIGHT CURING NOTE:** Light curing of applied XP BOND™ Universal Total-Etch Adhesive adhesive/activator mixture is not necessary when used in conjunction with DENTSPLY manufactured dual cure resin cement. If curing is desired, cure mixed adhesive/activator for 10 seconds' using a curing light.
 - 6.4 **Preparation of restoration**
 - 6.4.1 Treat surface of restoration according to manufacturers or dental laboratory's instructions, i.e., etching, mechanical roughening and/or Calibra® Silane Coupling Agent (available separately, see complete *Directions for Use*) application.
 - 6.4.2 Apply a single coat of mixed adhesive/activator to the internal bonding surface of the restoration. Immediately air dry for 5 seconds.
 - 6.4.3 Light curing of applied XP BOND™ Universal Total-Etch Adhesive adhesive/activator mixture is not necessary when used in conjunction with DENTSPLY dual cure resin

cements. If light curing is desired, cure mixed adhesive/activator for 10 seconds¹ using a curing light.

6.5 **Cementation:** Prepare and apply dual cured resin cement, according to manufacturer's instructions.

7. Endodontic Post Cementation

7.1 **Cleaning:** See section 1.1

7.2 Tooth Conditioner/Dentin Pretreatment

7.2.1 Rinse and thoroughly dry the prepared post preparation space (using air and paper points).

7.2.2 Apply Caulk® 34% Tooth Conditioner Gel (34% phosphoric acid). Attach disposable needle to end of syringe. Needle tip may be bent for easy access. Gently extrude Caulk® 34% Tooth Conditioner Gel to the post space and maintain contact for 15 seconds followed by a 15-second rinse. The preparation post space should then be dried with a gentle air blast and paper points to remove residual moisture, but do not desiccate the conditioned dentin surface. Once the surfaces have been properly treated, they must be kept uncontaminated. If salivary contamination occurs, repeat procedure beginning at Step 7.2.

7.3 Application of XP BOND™ Universal Total-Etch Adhesive

7.3.1 Place 1-2 drops of XP BOND™ Universal Total-Etch Adhesive into a clean Clixdish™ Mixing Well or standard plastic mixing well. Replace cap promptly.

7.3.2 Place an equal number of drops of Self Cure Activator into the same mixing well. Replace cap promptly. Mix contents for 1-2 seconds with a clean, unused brush tip.

7.3.3 Apply mixed adhesive/activator to post preparation with the brush provided, being sure to apply generous amounts to the preparation orifice. A paper point pre-wetted with the adhesive mixture may aid in bringing the adhesive mixture down to the deepest portion of the preparation. Avoid pooling. Maintain contact of adhesive/activator with tooth structure for at least 20 seconds.

7.3.4 Remove solvent by gently drying with clean, dry air from a dental syringe for at least 5 seconds. Surface should have a uniform glossy appearance. If not, repeat application and air dry. Surface should not show areas of excessive adhesive thickness or pooling. Repeat air drying/evaporation outlined above if necessary. Use of clean, dry paper points may aid in thorough removal of solvent/excess adhesive in post space. **LIGHT CURING NOTE:** Light curing of applied XP BOND™ Universal Total-Etch Adhesive adhesive/activator mixture is not necessary when used in conjunction with DENTSPLY manufactured dual cure resin cements or restoratives. If curing is desired, cure mixed adhesive/activator for 10 seconds¹ using a curing light.

7.4 Preparation of post

7.4.1 Treat surface of post according to manufacturers or dental laboratory's instructions, i.e., etching, mechanical roughening and/or Calibra® Silane Coupling Agent (available separately, see *complete Directions for Use*) application.

7.4.2 Apply a single coat of mixed adhesive/activator to the post. Immediately air dry for 5 seconds.

7.4.3 Light curing of applied XP BOND™ Universal Total-Etch Adhesive adhesive/activator mixture is not necessary when used in conjunction with DENTSPLY dual cure resin cements or restoratives. If curing is desired, cure mixed adhesive/activator for 10 seconds¹ using a curing light.

7.5 Post Cementation

7.5.1 Mix dual cured resin cement components according to manufacturer's directions and spread on surface of post and/or into the post preparation with a syringe tip, Lentulo Spiral, or metal file.

7.5.2 Seat post immediately. Clean up excess with appropriate instruments.

7.5.3 Light cure the coronal portion of cemented post for 20 seconds to aid in post stabilization once fully seated.

7.5.4 Proceed with core build-up and/or preparation as directed by resin cement manufacturer's directions.

8. Adhesive bonding of direct amalgam restorations

8.1 **Preparation:** Finish preparation by removing existing restorations and/or caries.

8.2 **Cleaning:** Clean preparation and place Dycal® Liner if needed, following Section 1.1 and 1.2.

- 8.3 **Tooth Conditioning/Dentin Pretreatment:** When used as a bonding agent for amalgam materials, it is recommended to follow the total etch technique described in Section 1.3. Once the surfaces have been properly treated, they must be kept uncontaminated. If salivary contamination occurs, repeat procedure beginning at Step 8.2.
- 8.4 **Application of XP BOND™ Universal Total-Etch Adhesive:** When used as a bonding agent for amalgam materials, it is recommended to follow the dual cure mixed adhesive/activator application technique described in Section 5.5.
- 8.5 **Application of Amalgam Bonding Base and Amalgam Bonding Catalyst**
- 8.5.1 Dispense two drops of Amalgam Bonding Base into a separate, clean plastic mixing well. Replace cap securely.
- 8.5.2 Dispense two drops of Amalgam Bonding Catalyst into the same mixing well. Replace cap securely. Mix contents of plastic well for 1 to 2 seconds with new, clean disposable brush tip.
- 8.5.3 Using the disposable brush, apply the mixed Amalgam Bonding Agents by coating the entire preparation.
- 8.6 **Completion:** Immediately begin placing and condensing amalgam (e.g. Dispersalloy® Dispersed Phase Alloy) as per manufacturer's directions.

CLEANING AND DISINFECTION

To prevent XP BOND™ Universal Total-Etch Adhesive bottles from exposure to spatter or spray of body fluids or contaminated hands, or oral tissues, use of a protective barrier is recommended to avoid package contamination. Repeated disinfection may damage label.

Do not attempt to clean, disinfect or re-use applicator brush or unit dose container. Properly dispose used brushes and containers.

The CliXdish™ Mixing Well may be cleaned by scrubbing with hot water and soap or detergent. Disinfect or sterilize as outlined below.

Disinfection OF CliXdish™ Mixing Well

The CliXdish™ Mixing Well if exposed to spatter or spray of body fluids or that may have been touched by contaminated hands, or oral tissues, should be disinfected with a hospital-level disinfectant. Acceptable disinfectants are EPA-registered as tuberculocidal. Iodophors, sodium hypochlorite (5.25%), chlorine dioxide and dual or synergized quaternaries are approved disinfectants. Disinfect the mixing well by immersing it in any recommended hospital-level disinfectant except neutral glutaraldehyde for the contact time recommended by the disinfectant manufacturer for optimum results. Some phenolic-based agents and iodophor-based products may cause surface staining. Agents containing organic solvents, such as alcohol, may tend to dissolve the plastic. The disinfectant manufacturer's directions should be followed properly for optimum results. Water-based disinfectant solutions are preferred.

Alternatively, the CliXdish™ Mixing Well may be sterilized by autoclave (275°F/135°C – 280°F/138°C) for up to 20 times. Allow CliXdish™ Mixing Well to dry thoroughly before storage.

LOT NUMBER AND EXPIRATION DATE

1. Do not use after expiration date. ISO standard is used: "YYYY/MM"
2. The following numbers should be quoted in all correspondence:
 - Reorder Number
 - Lot number on bottle/unit dose
 - Expiration date on bottle/unit dose

¹ Check curing light for minimum curing output of at least 800 mw/cm². Cure for at least 20 seconds if light output is between 500 and 800 mw/cm².